

AMENDMENTS TO THE CLAIMS

1-2. (Cancelled)

3. (Withdrawn) A roll-off reducing agent comprising an inorganic compound having a property of controlling a surface potential of an abrasive in a polishing composition, wherein a surface potential of the abrasive in a standard polishing composition is controlled -110 to 250 mV by the presence of the inorganic compound, wherein the standard polishing composition is prepared which comprises 20 parts by weight of an abrasive, said abrasive being high-purity alumina having Al_2O_3 purity of 98.0% by weight or more composed of α -type co-random crystal, 1 part by weight of citric acid, 78 parts by weight of water and 1 part by weight of an inorganic compound.

4. (Withdrawn) The roll-off reducing agent according to claim 3, wherein the inorganic compound is at least one compound selected from the group consisting of a nitrogen-containing inorganic acid or a salt thereof, a sulfur-containing inorganic acid or a salt thereof, a phosphorus-containing inorganic acid or a salt thereof, a halogen-containing inorganic acid or a salt thereof, a carbonate, a cyanate, and a metal atom-containing inorganic acid or a salt thereof.

5. (Withdrawn) The roll-off reducing agent according to claim 3 or 4, wherein the inorganic compound is sulfuric acid or a sulfate.

6-9. (Cancelled)

10. (Withdrawn) A process for producing a substrate comprising a step of polishing a substrate to be polished with the polishing composition of claim 1 or 2.

11. (Withdrawn) A process for producing a substrate comprising a step of polishing a substrate to be polished with the polishing composition of claim 6.

12. (Withdrawn) The process according to claim 10, wherein the substrate to be polished is a magnetic disk substrate.

13. (Withdrawn) The process according to claim 11, wherein the substrate to be polished is a magnetic disk substrate.

14. (Withdrawn) A process of reducing roll-off of a substrate, comprising applying to a substrate to be polished a polishing liquid comprising the roll-off reducing agent as defined in claim 3 or 4 in the polishing step.

15. (Withdrawn) A process of reducing roll-off of a substrate, comprising applying to a substrate to be polished the polishing composition as defined in claim 1 or 2 in the polishing step.

16. (New) A polishing composition comprising:

a roll-off reducing agent comprising an inorganic compound having a property of controlling a surface potential of an abrasive in a polishing composition, wherein a surface potential of the abrasive in a standard polishing composition is controlled to -110 to 250 mV by the presence of the inorganic compound, wherein the standard polishing composition is prepared which comprises 20 parts by weight of an abrasive, said abrasive being high-purity alumina having Al₂O₃ purity of 98.0% by weight or more composed of α -type co-random crystal, 1 part by weight of citric acid, 78 parts by weight of water and 1 part by weight of an inorganic compound.

17. (New) A polishing composition according to claim 16, wherein the inorganic compound is at least one compound selected from the group consisting of a nitrogen-containing inorganic acid or a salt thereof, a sulfur-containing inorganic acid or a salt thereof, a phosphorus-containing inorganic acid or a salt thereof, a halogen-containing inorganic acid or a salt thereof, a carbonate, a cyanate, and a metal atom-containing inorganic acid or a salt thereof.

18. (New) The polishing composition according to claim 16, further comprising an abrasive, an organic acid or a salt thereof, and water.

19. (New) The polishing composition according to claim 18, wherein the abrasive is alumina.

20. (New) The polishing composition according to claim 18, wherein the organic acid or the salt thereof is at least one compound selected from the group consisting of a monocarboxylic acid and polycarboxylic acid having either OH group or groups or SH group or groups, a dicarboxylic acid having 2 to 3 carbon atoms and having neither OH group or groups nor SH group or groups, a monocarboxylic acid having neither OH group or groups nor SH group or groups and a salt thereof.

21. (New) The polishing composition according to claim 20, wherein the organic acid is at least one compound selected form the group consisting of glycolic acid, mercaptosuccinic acid, thioglycolic acid, lactic acid, β -hydroxypropionic acid, malic acid, tartaric acid, citric acid, isocitric acid, allocitric acid, gluconic acid, glyoxylic acid, glyceric acid, mandelic acid, tropic acid, benzilic acid, salicylic acid, formic acid, acetic acid, propionic acid, butyric acid, isobutyric acid, valeric acid, isovaleric acid, hexanoic acid, heptanoic acid, 2-methylhexanoic acid, octanoic acid, 2-ethylhexanoic acid, nonanoic acid, decanoic acid and lauric acid.